



Material Content Data Sheet



Sales Product Name		ESD112-B1-02EL E6327		Issued		29. August 2013		
MA#		MA001115896						
Package		PG-TSLP-2-20		Weight*		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.11		1138	
	noble metal	gold	7440-57-5	0.003	0.44		4415	
	inorganic material	silicon	7440-21-3	0.020	3.27	3.82	32715	38268
leadframe	non noble metal	nickel	7440-02-0	0.241	39.27	39.27	392669	392669
wire	noble metal	gold	7440-57-5	0.005	0.87	0.87	8728	8728
encapsulation	organic material	carbon black	1333-86-4	0.002	0.26		2605	
	plastics	epoxy resin	-	0.046	7.56		75552	
	inorganic material	silicondioxide	60676-86-0	0.271	44.29	52.11	442884	521041
leadfinish	noble metal	gold	7440-57-5	0.010	1.70	1.70	17003	17003
plating	noble metal	palladium	7440-05-3	0.003	0.53		5288	
	noble metal	gold	7440-57-5	0.010	1.70	2.23	17003	22291
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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